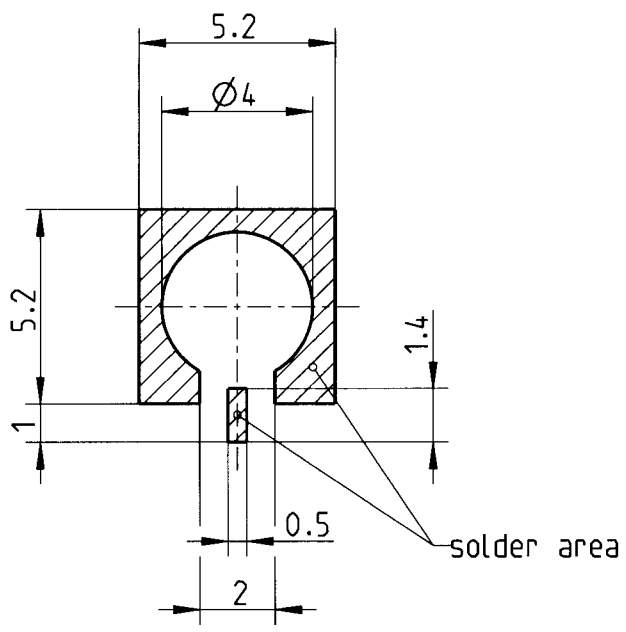


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Leiterplatten-Layout
PCB layout
B 120



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formzahl: T.C. 05.05.05.01.1
Date: A. E. METZEL, EDB, PH
Version: 1.0

-METRIC-



ISO-Projekt: 01
Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		<i>general tolerance</i> ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		<i>scale:</i> 5:1	<i>weight(g):</i> <i>surface(mm²):</i>
		<i>material:</i>			
		<i>date</i> <i>name</i>		Leiterplatten-Layout PCB layout	
		<i>drawn</i> 14.11.2005 A_Nobis			
		<i>check.</i> 30.11.05 <i>[Signature]</i>			
		<i>appr.</i> 2/12/05 <i>[Signature]</i>			
		<i>dimensioning incl. finish</i>		<i>part-no.:</i> MB_120	
a00 05-0615 A_Nobis 15.11.2005	<i>distribu-</i> <i>tion to:</i> FE AZ QSM RMT .	<i>remarks:</i>			
<i>rev.</i> <i>change-no</i> <i>name</i> <i>date</i>			X 	<i>of:</i> 1	